

### Feature

- The chips are electrically insulated from bottom plate, 2500V AC voltage
- Complete pressure connection structure, with excellent temperature Characteristics and power cycling capacity
- Forced air cooling for modules below 400A and air cooling or water Cooling for modules above 500A

### Typical application

- DC power supplies of appliances and devices
- AC and DC motor control, Soft starting for motors
- Various rectifying power supply
- Electric welders, Frequency transformers, Battery charging and discharging

I <sub>F(AV)</sub>	55A
V <sub>RRM</sub>	500-2500V
I <sub>FSM</sub>	1.3 KA
I <sup>2</sup> t	8.6 10 <sup>3</sup> a <sup>2</sup> s

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T <sub>J</sub> (°C)	VALUE		UNIT
				Min	Max	
I <sub>F(AV)</sub>	Mean forward current	180° half sine wave, 50HZ Single heat sink, T <sub>C</sub> =98°C	150		55	A
I <sub>T(RMS)</sub>	RMS current		150		86	A
V <sub>RRM</sub>	Repetitive peak reverse voltage	V <sub>DRM</sub> &V <sub>RRM</sub> tp=10ms V <sub>DSM</sub> &V <sub>RSM</sub> =V <sub>DRM</sub> &V <sub>RRM</sub> +200V	150	500	2500	V
I <sub>RRM</sub>	Repetitive peak current	V <sub>RM</sub> =0V <sub>RRM</sub>	150		8	mA
I <sub>FSM</sub>	Surge on-state current	10ms half sine wave V <sub>R</sub> =0.6V <sub>RRM</sub>	150		1.3	KA
I <sup>2</sup> t	I <sup>2</sup> t for fusing coordination				8.6	A <sup>2S*10</sup>
V <sub>TO</sub>	Threshold voltage		150		0.80	V
r <sub>T</sub>	On-state slop resistance				3.47	mΩ
V <sub>FM</sub>	Peak on-state voltage	I <sub>TM</sub> =170A	25		1.46	V
R <sub>th(j-c)</sub>	Thermal impedance node to the shell	180 ° sine wave, single heat sink			0.77	°C/W
R <sub>th(e-h)</sub>	Thermal impedance ( shell to powder)	180 ° sine wave, single heat sink			0.2	°C/W
V <sub>iso</sub>	Insulation voltage			2500		V
F <sub>M</sub>	Mounting force (M5)				4	N-m
	Mounting force (M6)				6	N-m
T <sub>stq</sub>	Stored temperature			-40	125	°C
W <sub>t</sub>	Weight					g
Outline						

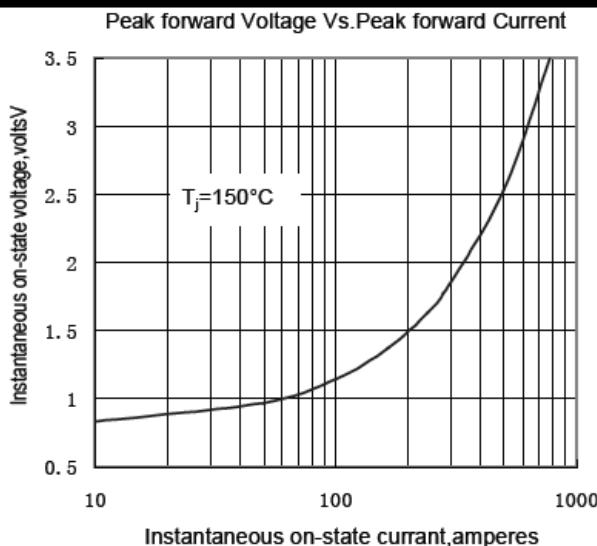


Fig.1

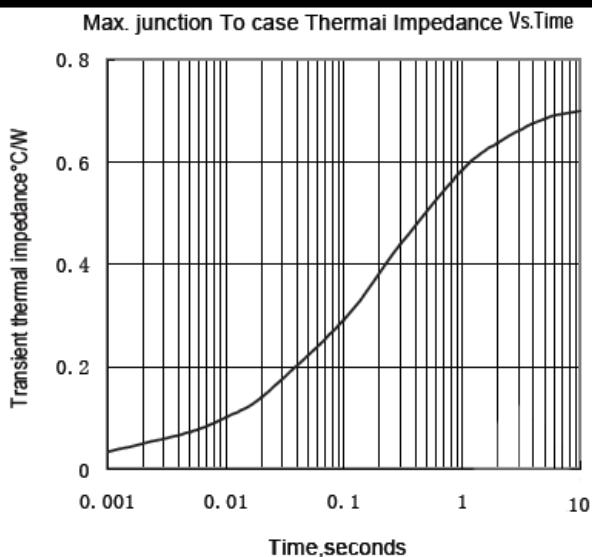


Fig.2

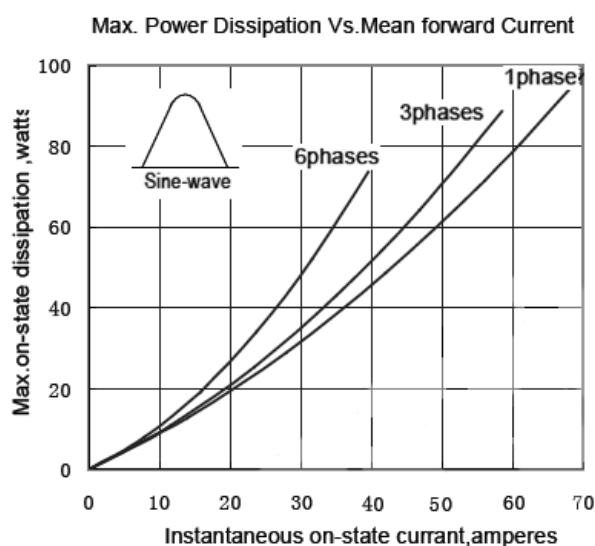


Fig.1

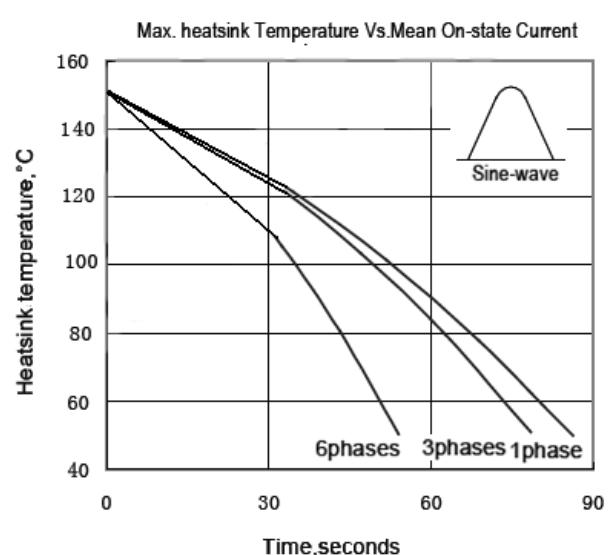


Fig.2

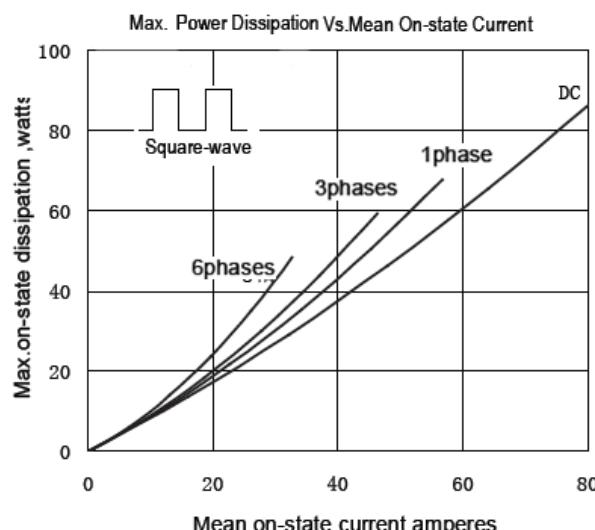


Fig.5

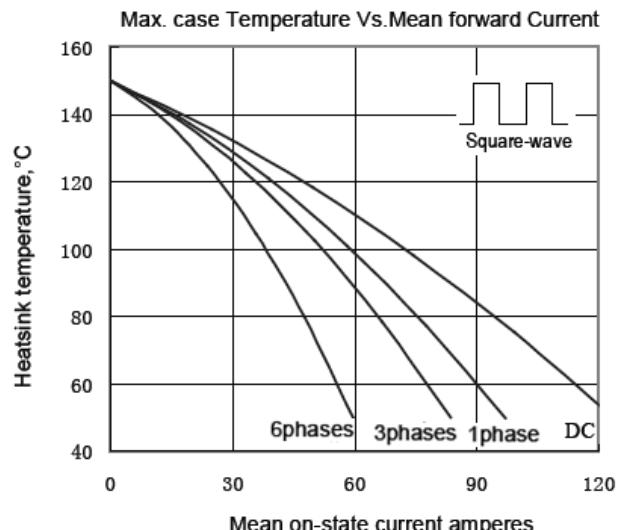


Fig.6

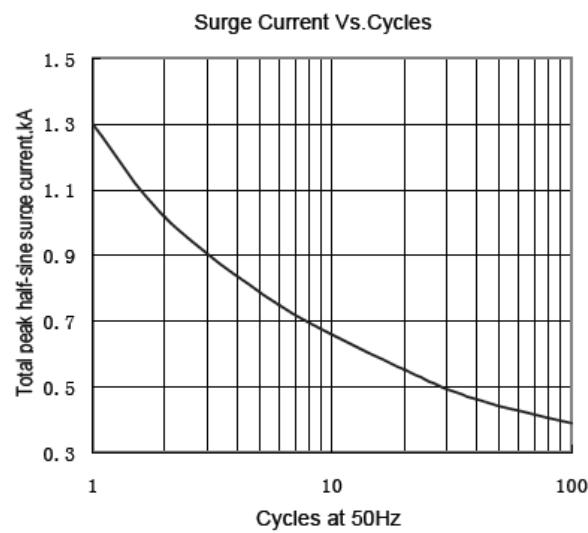


Fig.7

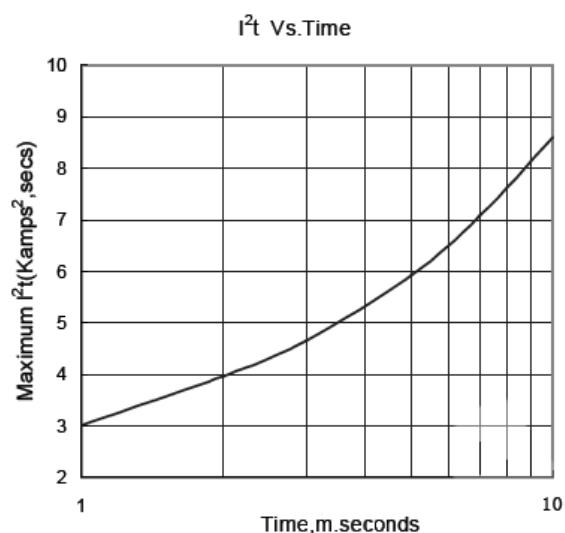
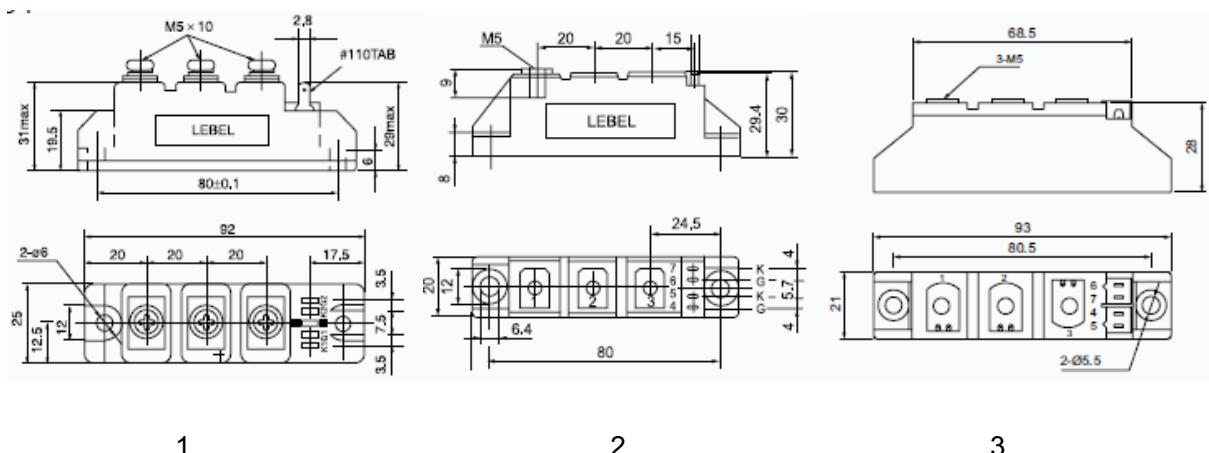


Fig.8

### Outline:



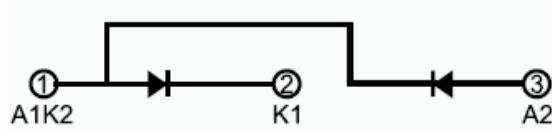
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2

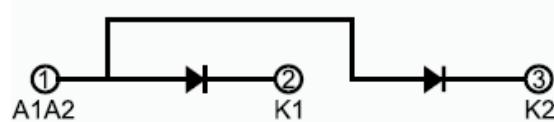
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### Circuit Drawing:

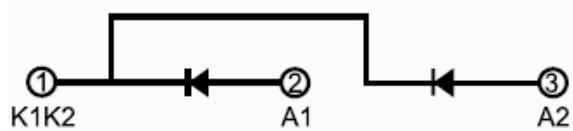
#### MDC



#### MDA



#### MDK



#### MD

